### Features

- Fast Read Access Time 70 ns
- Dual Voltage Range Operation
  - Unregulated Battery Power Supply Range, 2.7V to 3.6V or Standard 5V  $\pm\,10\%$  Supply Range
- Pin Compatible with JEDEC Standard AT27C512R
- Low Power CMOS Operation
  - 20  $\mu$ A Max (Less than 1  $\mu$ A Typical) Standby for V<sub>CC</sub> = 3.6V
  - 29 mW Max Active at 5 MHz for V<sub>CC</sub> = 3.6V
- JEDEC Standard Surface Mount Packages
  - 32-lead PLCC
  - 28-lead SOIC
  - 28-lead TSOP
- High Reliability CMOS Technology
  - 2,000V ESD Protection
  - 200 mA Latchup Immunity
- Rapid Programming Algorithm 100 µs/Byte (Typical)
- CMOS and TTL Compatible Inputs and Outputs
  - JEDEC Standard for LVTTL and LVBO
- Integrated Product Identification Code
- Industrial Temperature Range
- Green (Pb/Halide-free) Packaging Option

### 1. Description

The AT27BV512 is a high-performance, low-power, low-voltage 524,288-bit one-time programmable read-only memory (OTP EPROM) organized as 64K by 8 bits. It requires only one supply in the range of 2.7 to 3.6V in normal read mode operation, making it ideal for fast, portable systems using either regulated or unregulated battery power.

Atmel's innovative design techniques provide fast speeds that rival 5V parts while keeping the low power consumption of a 3V supply. At  $V_{CC} = 2.7V$ , any byte can be accessed in less than 70 ns. With a typical power consumption of only 18 mW at 5 MHz and  $V_{CC} = 3V$ , the AT27BV512 consumes less than one fifth the power of a standard 5V EPROM.

Standby mode supply current is typically less than 1  $\mu$ A at 3V. The AT27BV512 simplifies system design and stretches battery lifetime even further by eliminating the need for power supply regulation.

The AT27BV512 is available in industry-standard JEDEC-approved one-time programmable (OTP) plastic PLCC, SOIC, and TSOP packages. All devices feature two-line control ( $\overline{CE}$ ,  $\overline{OE}$ ) to give designers the flexibility to prevent bus contention.

The AT27BV512 operating with V<sub>CC</sub> at 3.0V produces TTL level outputs that are compatible with standard TTL logic devices operating at V<sub>CC</sub> = 5.0V. At V<sub>CC</sub> = 2.7V, the part is compatible with JEDEC approved low voltage battery operation (LVBO) interface specifications. The device is also capable of standard 5-volt operation making it ideally suited for dual supply range systems or card products that are pluggable in both 3-volt and 5-volt hosts.



512K (64K x 8) Unregulated Battery-Voltage High-Speed OTP EPROM

### AT27BV512

0602E-EPROM-12/07



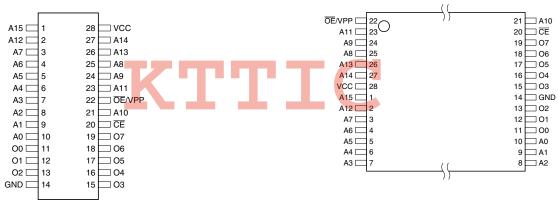
Atmel's AT27BV512 has additional features to ensure high quality and efficient production use. The Rapid Programming Algorithm reduces the time required to program the part and guarantees reliable programming. Programming time is typically only 100  $\mu$ s/byte. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry-standard programming equipment to select the proper programming algorithms and voltages. The AT27BV512 programs exactly the same way as a standard 5V AT27C512R and uses the same programming equipment.

### 2. Pin Configurations

Pin Name	Function
A0 - A15	Addresses
00 - 07	Outputs
CE	Chip Enable
0E/VPP	Output Enable/Program Supply
NC	No Connect

#### 2.1 28-lead SOIC Top View

2.3 28-lead TSOP (Type 1) Top View



### 2.2 32-lead PLCC Top View

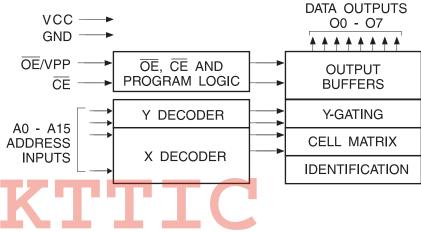
		<b>A7</b>	<b>A12</b>	🗆 A15	2 N		□ A14	□ A13	
	$ < \ $	4	с	2	-	N	3	0	
A6 🗆	5				0	0	0	29	9 🗆 A8
A5 🗆	6							28	3 🗆 A9
A4 🗆	7							2	7 🗆 A11
A3 🗆	8							26	5 🗆 NC
A2 🗆	9							25	
A1 🗆	10	)						24	4 🗆 A10
A0 🗆	1	1						23	
NC 🗆	12	2						22	2 🗆 07
O0 🗆	13	34	ß	9		8	6	2 <sup>.</sup>	1 🗆 O6
		÷	÷	÷	÷	÷	÷	20	
		0							
		6	02	UND NC	Z	03	ò	ö	

Note: PLCC package pins 1 and 17 are Don't Connect.

### 3. System Considerations

Switching between active and standby conditions via the Chip Enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed datasheet limits, resulting in device non-conformance. At a minimum, a 0.1  $\mu$ F high frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the V<sub>CC</sub> and Ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply voltage level on printed circuit boards with large EPROM arrays, a 4.7  $\mu$ F bulk electrolytic capacitor should be utilized, again connected between the V<sub>CC</sub> and Ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

### 4. Block Diagram



### 5. Absolute Maximum Ratings\*

Temperature Under Bias	40°C to +85°C
Storage Temperature	65°C to +125°C
Voltage on Any Pin with Respect to Ground	2.0V to +7.0V <sup>(1)</sup>
Voltage on A9 with Respect to Ground	2.0V to +14.0V <sup>(1)</sup>
V <sub>PP</sub> Supply Voltage with Respect to Ground	2.0V to +14.0V <sup>(1)</sup>

\*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability

Notes: 1. Minimum voltage is -0.6V DC which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is V<sub>CC</sub> + 0.75V DC which may be exceeded if certain precautions are observed (consult application notes) and which may overshoot to +7.0V for pulses of less than 20 ns.





### 6. Operating Modes

Mode \ Pin	CE	OE/V <sub>PP</sub>	Ai	V <sub>cc</sub>	Outputs
Read <sup>(2)</sup>	V <sub>IL</sub>	V <sub>IL</sub>	Ai	V <sub>CC</sub>	D <sub>OUT</sub>
Output Disable <sup>(2)</sup>	V <sub>IL</sub>	V <sub>IH</sub>	X <sup>(1)</sup>	V <sub>cc</sub>	High Z
Standby <sup>(2)</sup>	V <sub>IH</sub>	Х	X	V <sub>CC</sub>	High Z
Rapid Program <sup>(3)</sup>	V <sub>IL</sub>	V <sub>PP</sub>	Ai	V <sub>cc</sub>	D <sub>IN</sub>
PGM Verify <sup>(3)</sup>	V <sub>IL</sub>	V <sub>IL</sub>	Ai	V <sub>cc</sub>	D <sub>OUT</sub>
PGM Inhibit <sup>(3)</sup>	V <sub>IH</sub>	V <sub>PP</sub>	х	$V_{CC}$	High Z
Product Identification <sup>(3)(5)</sup>	V <sub>IL</sub>	V <sub>IL</sub>	$A9 = V_{H}^{(4)}$ $A0 = V_{IH} \text{ or } V_{IL}$ $A1 - A15 = V_{IL}$	V <sub>CC</sub>	Identification Code

Notes: 1. X can be  $V_{IL}$  or  $V_{IH}$ .

2. Read, output disable, and standby modes require, 2.7V  $\leq$ V<sub>CC</sub>  $\leq$ 3.6V, or 4.5V  $\leq$ V<sub>CC</sub>  $\leq$ 5.5V.

3. Refer to Programming Characteristics. Programming modes require  $V_{CC}$  = 6.5V.

- 4.  $V_{H} = 12.0 \pm 0.5 V.$
- 5. Two identifier bytes may be selected. All Ai inputs are held low ( $V_{IL}$ ), except A9 which is set to  $V_H$  and A0 which is toggled low ( $V_{IL}$ ) to select the Manufacturer's Identification byte and high ( $V_{IH}$ ) to select the Device Code byte.

### 7. DC and AC Operating Conditions for Read Operation

		AT27BV512-70
Operating Temperature (Case)	77 00 00 7	-40°C - 85°C
		2.7V to 3.6V
V <sub>CC</sub> Power Supply		5V ±10%

### 4 **AT27BV512**

### 8. DC and Operating Characteristics for Read Operation

Symbol	Parameter	Condition	Min	Max	Units
$V_{\rm CC} = 2.7$	V to 3.6V				
ILI	Input Load Current	$V_{IN} = 0V$ to $V_{CC}$		±1	μA
I <sub>LO</sub>	Output Leakage Current	$V_{OUT} = 0V$ to $V_{CC}$		±5	μA
I <sub>PP1</sub> <sup>(2)</sup>	V <sub>PP</sub> <sup>(1)</sup> Read/Standby Current	V <sub>PP</sub> = V <sub>CC</sub>		10	μA
		$I_{SB1}$ (CMOS), $\overline{CE} = V_{CC \pm} 0.3V$		20	μA
I <sub>SB</sub>	V <sub>CC</sub> <sup>(1)</sup> Standby Current	$I_{SB2}$ (TTL), $\overline{CE} = 2.0$ to $V_{CC} + 0.5V$		100	μA
I <sub>cc</sub>	V <sub>CC</sub> Active Current	f = 5 MHz, $I_{OUT}$ = 0 mA, $\overline{CE}$ = $V_{IL}$ , $V_{CC}$ = 3.6V		8	mA
N/		V <sub>CC</sub> = 3.0 to 3.6V	-0.6	0.8	V
V <sub>IL</sub>	Input Low Voltage	V <sub>CC</sub> = 2.7 to 3.6V	-0.6	0.2 x V <sub>CC</sub>	V
	land that Make as	V <sub>CC</sub> = 3.0 to 3.6V	2.0	V <sub>CC</sub> + 0.5	V
V <sub>IH</sub>	Input High Voltage	V <sub>CC</sub> = 2.7 to 3.6V	0.7 x V <sub>CC</sub>	V <sub>CC</sub> + 0.5	V
		I <sub>OL</sub> = 2.0 mA		0.4	V
V <sub>OL</sub> Output Low Voltage	Output Low Voltage	I <sub>OL</sub> = 100 μA		0.2	V
		I <sub>OL</sub> = 20 μA		0.1	V
		I <sub>OH</sub> = -2.0 mA	2.4		V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -100 μA	V <sub>CC</sub> - 0.2		V
	_	I <sub>OH</sub> = -20 μA	V <sub>CC</sub> - 0.1		V
V <sub>CC</sub> = 4.5	/ to 5.5V				
I <sub>LI</sub>	Input Load Current	$V_{IN} = 0V$ to $V_{CC}$		±1	μA
I <sub>LO</sub>	Output Leakage Current	$V_{OUT} = 0V$ to $V_{CC}$		±5	μA
I <sub>PP1</sub> <sup>(2)</sup>	V <sub>PP</sub> <sup>(1)</sup> Read/Standby Current	$V_{PP} = V_{CC}$		10	μA
	V <sub>CC</sub> <sup>(1)</sup> Standby Current	$I_{SB1}$ (CMOS), $\overline{CE} = V_{CC} \pm 0.3V$		100	μA
I <sub>SB</sub>	V <sub>CC</sub> / Standby Current	$I_{SB2}$ (TTL), $\overline{CE}$ = 2.0 to $V_{CC}$ + 0.5V		1	mA
I <sub>CC</sub>	V <sub>CC</sub> Active Current	f = 5 MHz, $I_{OUT}$ = 0 mA, $\overline{CE}$ = $V_{IL}$		20	mA
V <sub>IL</sub>	Input Low Voltage		-0.6	0.8	V
V <sub>IH</sub>	Input High Voltage		2.0	V <sub>CC</sub> + 0.5	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1 mA		0.4	V
V <sub>OH</sub>	Output High Voltage	Ι <sub>OH</sub> = -400 μΑ	2.4		V

Notes: 1.  $V_{CC}$  must be applied simultaneously with or before  $\overline{OE}/V_{PP}$  and removed simultaneously with or after  $\overline{OE}/V_{PP}$ 

2. V<sub>PP</sub> may be connected directly to V<sub>CC</sub>, except during programming. The supply current would then be the sum of I<sub>CC</sub> and I<sub>PP</sub>



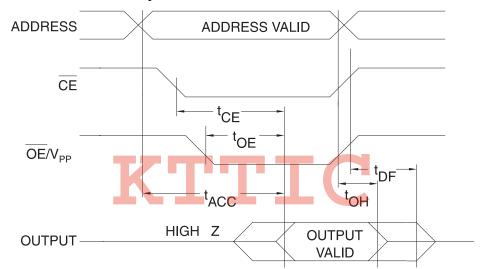


### 9. AC Characteristics for Read Operation

 $V_{CC}$  = 2.7V to 3.6V and 4.5V to 5.5V

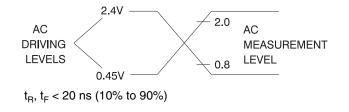
			AT27B\	AT27BV512-70	
Symbol	Parameter	Condition	Min	Max	Units
t <sub>ACC</sub> <sup>(3)</sup>	Address to Output Delay	$\overline{CE} = \overline{OE} / V_{PP} = V_{IL}$		70	ns
t <sub>CE</sub> <sup>(2)</sup>	CE to Output Delay	$\overline{OE}/V_{PP} = V_{IL}$		70	ns
t <sub>OE</sub> <sup>(2)(3)</sup>	OE/V <sub>PP</sub> to Output Delay	$\overline{CE} = V_{IL}$		50	ns
t <sub>DF</sub> <sup>(4)(5)</sup>	$\overline{OE}/V_{PP}$ or $\overline{CE}$ High to Output Float, Whichever Occurred First			40	ns
t <sub>OH</sub>	Output Hold from Address, $\overline{CE}$ or $\overline{OE}/V_{PP}$ Whichever Occurred First		0		ns

### **10.** AC Waveforms for Read Operation<sup>(1)</sup>

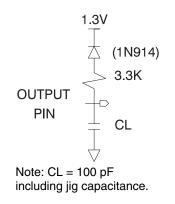


- Notes: 1. Timing measurement references are 0.8V and 2.0V. Input AC drive levels are 0.45V and 2.4V, unless otherwise specified.
  - 2.  $\overline{OE}/V_{PP}$  may be delayed up to  $t_{CE}$   $t_{OE}$  after the falling edge of  $\overline{CE}$  without impact on  $t_{CE}$ .
  - 3.  $\overline{OE}/V_{PP}$  may be delayed up to  $t_{ACC}$   $t_{OE}$  after the address is valid without impact on  $t_{ACC}$ .
  - 4. This parameter is only sampled and is not 100% tested.
  - 5. Output float is defined as the point when data is no longer driven.
  - 6. When reading a AT27BV256, a 0.1 μF capacitor is required across V<sub>CC</sub> and ground to suppress spurious voltage transients.

### **11. Input Test Waveform and Measurement Level**



### 12. Output Test Load



### 13. Pin Capacitance

f = 1 MHz, T = 25°C<sup>(1)</sup>

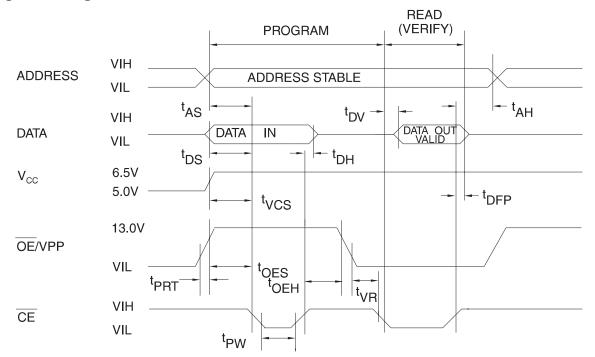
$I = I I V \square Z, I$	= 25 C ( )			
Symbol	Тур	Мах	Units	Conditions
C <sub>IN</sub>	4	6	pF	$V_{IN} = 0V$
C <sub>OUT</sub>	8	12	pF	$V_{OUT} = 0V$

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.





### 14. Programming Waveforms<sup>(1)</sup>



- Notes: 1. The Input Timing Reference is 0.8V for  $V_{\rm IL}$  and 2.0V for  $V_{\rm IH}.$ 
  - 2.  $t_{OE}$  and  $t_{DFP}$  are characteristics of the device but must be accommodated by the programmer.
  - 3. When programming the AT27BV512, a 0.1 µF capacitor is required across V<sub>PP</sub> and ground to suppress spurious voltage transients.

### **15. DC Programming Characteristics**

 $T_A = 25 \pm 5^{\circ}C, V_{CC} = 6.5 \pm 0.25V, \overline{OE}/V_{PP} = 13.0 \pm 0.25V$ 

			Lii		
Symbol	Parameter	Test Conditions	Min	Мах	Units
ILI	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		±10	μA
V <sub>IL</sub>	Input Low Level		-0.6	0.8	V
V <sub>IH</sub>	Input High Level		2.0	V <sub>CC</sub> + 0.5	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1 mA		0.4	V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -400 μA	2.4		V
I <sub>CC2</sub>	V <sub>CC</sub> Supply Current (Program and Verify)			25	mA
I <sub>PP2</sub>	OE/V <sub>PP</sub> Current	$\overline{CE} = V_{IL}$		25	mA
V <sub>ID</sub>	A9 Product Identification Voltage		11.5	12.5	V

### **16. AC Programming Characteristics**

 ${\rm T_A} = 25 \pm 5^{\circ}{\rm C}, \, {\rm V_{CC}} = 6.5 \pm 0.25 {\rm V}, \, \overline{\rm OE} / {\rm V_{PP}} = 13.0 \pm 0.25 {\rm V}$ 

			Lin		
Symbol	Parameter	Test Conditions <sup>(1)</sup>	Min	Max	Units
t <sub>AS</sub>	Address Setup Time		2		μs
t <sub>OES</sub>	OE/V <sub>PP</sub> Setup Time		2		μs
t <sub>OEH</sub>	OE/V <sub>PP</sub> Hold Time	Input Rise and Fall Times:	2		μs
t <sub>DS</sub>	Data Setup Time	(10% to 90) 20 ns	2		μs
t <sub>AH</sub>	Address Hold Time	Input Pulse Levels:	0		μs
t <sub>DH</sub>	Data Hold Time	0.45V to 2.4V	2		μs
t <sub>DFP</sub>	CE High to Output Float Delay <sup>(2)</sup>		0	130	ns
t <sub>VCS</sub>	V <sub>CC</sub> Setup Time	Input Timing Reference Level: 0.8V to 2.0V	2		μs
t <sub>PW</sub>	CE Program Pulse Width <sup>(3)</sup>	0.00 10 2.00	95	105	μs
t <sub>DV</sub>	Data Valid from CE <sup>(2)</sup>	Output Timing Reference Level:		1	μs
t <sub>VR</sub>	OE/V <sub>PP</sub> Recovery Time	0.8V to 2.0V	2		μs
t <sub>PRT</sub>	OE/V <sub>PP</sub> Pulse Rise Time During Programming		50		ns

Notes: 1. V<sub>CC</sub> must be applied simultaneously or before OE/V<sub>PP</sub> and removed simultaneously or after OE/V<sub>PP</sub>

2. This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven – see timing diagram.

3. Program Pulse width tolerance is 100  $\mu sec \pm 5\%.$ 

### 17. Atmel's AT27BV512 Integrated Product Identification Code<sup>(1)</sup>

		Pins							Hex	
Codes	A0	07	O6	O5	O4	O3	02	01	00	Data
Manufacturer	0	0	0	0	1	1	1	1	0	1E
Device Type	1	0	0	0	0	1	1	0	1	0D

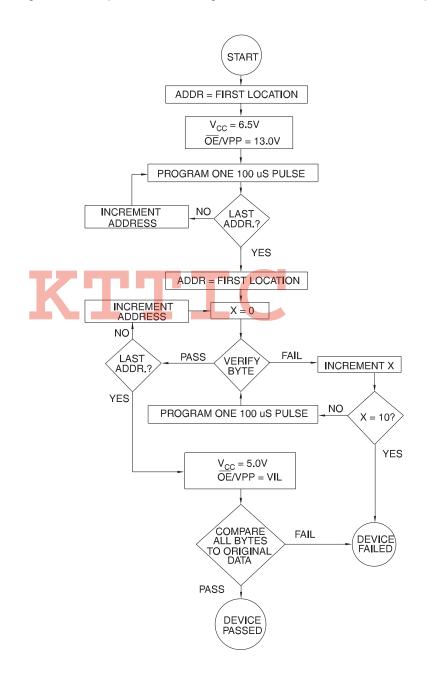
Note: 1. The AT27BV512 has the same Product Identification Code as the AT27C512R. Both are programming compatible.





### 18. Rapid Programming Algorithm

A 100  $\mu$ s  $\overline{CE}$  pulse width is used to program. The address is set to the first location. V<sub>CC</sub> is raised to 6.5V and  $\overline{OE}/V_{PP}$  is raised to 13.0V. Each address is first programmed with one 100  $\mu$ s  $\overline{CE}$  pulse without verification. Then a verification/reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 100  $\mu$ s pulses are applied with a verification after each pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked.  $\overline{OE}/V_{PP}$  is then lowered to V<sub>IL</sub> and V<sub>CC</sub> to 5.0V. All bytes are read again and compared with the original data to determine if the device passes or fails.



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http://www.lostelep.com.12107

11

http://www.kttic.com

### **19. Ordering Information**

### 19.1 Standard Package

t <sub>ACC</sub>	I <sub>CC</sub> (mA)		I <sub>CC</sub> (mA)			
(ns)	Active	Standby	Ordering Code	Package	Operation Range	
70	8	0.02	AT27BV512-70JI	32J	Industrial	
			AT27BV512-70RI	28R <sup>(1)</sup>	(-40°C to 85°C)	
			AT27BV512-70TI	28T		

Note:

Not recommended for new designs. Use Green package option.

#### 19.2 Green Package Option (Pb/Halide-free)

t <sub>ACC</sub>	I <sub>CC</sub> (mA)				
(ns)	Active	Standby	Ordering Code	Package	<b>Operation Range</b>
70	8	0.02	AT27BV512-70JU	32J	Industrial
			AT27BV512-70RU	28R <sup>(1)</sup>	(-40°C to 85°C)
			AT27BV512-70TU	28T	

Note: 1. The 28-pin SOIC package is not recommended for new designs.

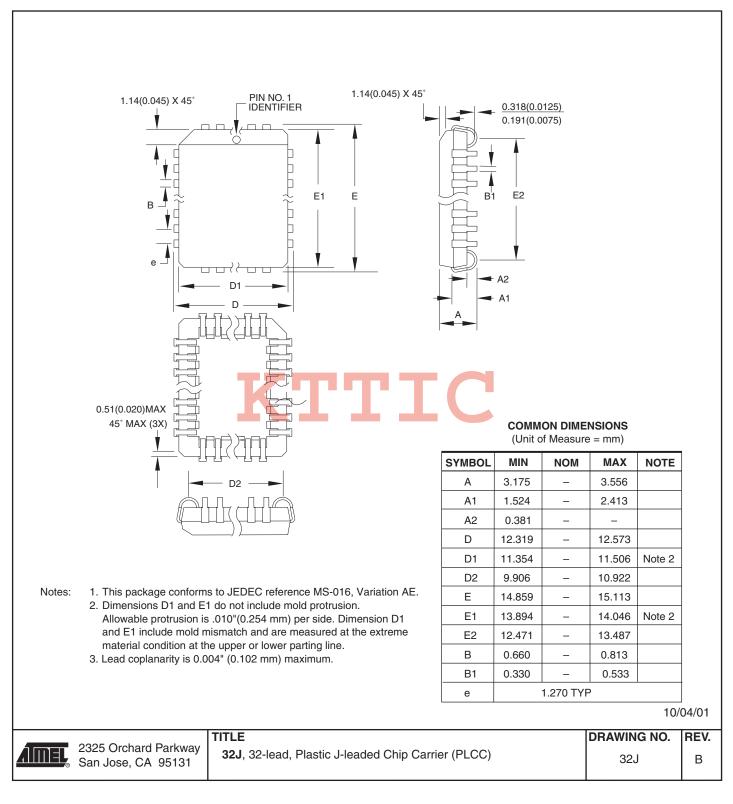
# KTTIC

Package Type				
32J	32-lead, Plastic J-leaded Chip Carrier (PLCC)			
28R	28-lead, 0.330" Wide, Plastic Gull Wing Small Package (SOIC)			
28T	28-lead, Plastic Thin Small Outline Package (TSOP)			



### 20. Packaging Information

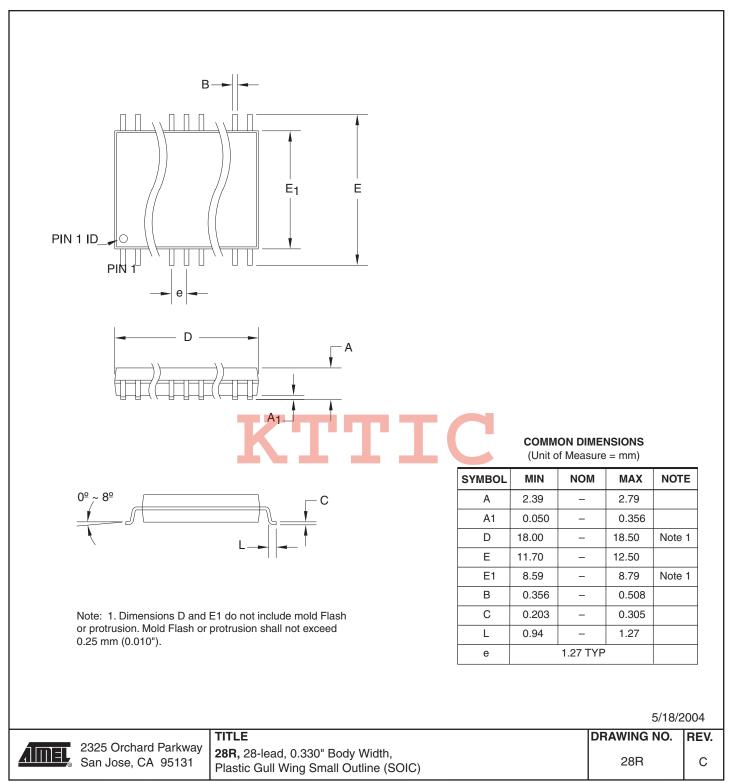
#### 20.1 32J - PLCC



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### AT27BV512

#### 20.2 28R - SOIC





#### 20.3 28T - TSOP

